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CLAIMS AS AMENDED

1-5. (Cancelled)

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6. (Currently Amended) A packaged ~~photosensitive element~~ photosensor device, comprising:

a first photosensitive element photosensor, having said first photosensor comprising first electrical connections; and

a second photosensor, said second photosensor comprising second electrical connections; and

a clear plastic package, having said photosensitive element mounted therein and having a plurality of surfaces, and providing a edge perimeter having supporting and enclosing said first and second photosensors, said clear plastic package comprising third electrical connections along edges of said an edge perimeter, which said third electrical connections are connected being electrically coupled to said first and second electrical connections on said photosensitive element, wherein said clear plastic package being clear at all locations within said perimeter, and is transparent in all directions and said first and second photosensors are configured to receive light from at least two opposite sides of said clear plastic package.

a second photosensitive element, receiving incoming light from a different direction and through a different surface than said photosensitive element.

7. (Currently Amended) A packaged ~~photosensitive element~~ CMOS imager array, comprising:

a photosensitive element photosensor, which element accumulates said photosensor being configured to accumulate charge using a photogate having and being electrically coupled to at least one first electrical connections connection; and

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a clear plastic quad flat package, ~~having said clear plastic quad flat package encapsulating said photosensitive element mounted therein;~~ photosensor and providing a comprising an edge perimeter, wherein said clear plastic quad flat package is transparent in all directions; and

C ~~having at least one second electrical connections connection along all edges of said edge perimeter, which connections are connected~~ said at least one second electrical connection being electrically coupled to said at least one first electrical connections on said photosensitive element connection; ~~said clear plastic package being clear at all locations within said perimeter.~~

8. (Currently Amended) A method of packaging an imager device, comprising:

~~obtaining an image sensor with electrical connections~~ providing an imager device;

forming a clear plastic quad flat package for said ~~image sensor, with said image sensor~~ imager device, wherein said imager device is totally encased within said clear plastic quad flat package;

forming electrical connections on edges of between a perimeter of said clear plastic quad flat package and said imager device;

~~connecting said electrical connections of said image sensor to said connections on said clear plastic package; and operating said image sensor~~ wherein said imager device is positioned to receive light that passes through said clear plastic quad flat package by accepting light from any of a plurality of different incoming angles which pass and through different surfaces of said clear plastic quad flat package.

9 and 10. (Cancelled)

11. (Currently Amended) A method of packaging an imager device, comprising:

~~obtaining an~~ providing a first image sensor with electrical connections comprises
~~obtaining first and second image sensors;~~

providing a second image sensor;

C/ forming a clear plastic package for totally enclosing said first image sensor and
said second image sensor, with said image sensor totally encased within said clear plastic
package; and

~~forming~~ providing electrical connections on edges of between said first and
second image sensors and a perimeter of said clear plastic package;

~~connecting said electrical connections of said image sensor to said connections~~
~~on said clear plastic package; and~~

~~operating said image sensor wherein said first and second image sensors are~~
positioned to receive light that passes through said clear plastic package, and using said first
image sensor being positioned to acquire light in from a first direction through said clear
plastic package and using said second image sensor being positioned to acquire light in
from a second direction through said clear plastic package different from said first direction.

12. (Currently Amended) An image sensor, comprising:

a first image sensor;

~~and a second image sensors~~ sensor; and

a third image sensor; and

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a clear plastic package for enclosing said first, ~~and~~ second, and third image sensors, said clear plastic package ~~packaging~~ and said first, ~~and~~ second, and third image sensors ~~with said first image sensor~~ configured for acquiring light ~~from~~ through a first side, a second side, and a third side of said clear plastic package, ~~and said second image sensor~~ acquiring light from a second, opposite side of said clear plastic package respectively, wherein said first, second, and third sides of said clear plastic package are different sides.

13. (Currently Amended) A sensor as in claim 12, wherein said clear plastic package has a perimeter surrounding said first, ~~and~~ second, and third image sensors, ~~and an edge of~~ said perimeter including and edge comprising electrical connections coupled to said first, ~~and~~ second, and third image sensors.

14. (Cancelled)

15. (Currently Amended) An image sensor as in claim 12, wherein said first, ~~and~~ second, and third image sensors are CMOS image sensors.

16. (Currently Amended) An image sensor as in claim 12, wherein said first, ~~and~~ second, and third image sensors acquire said image using photogates.

17 and 18. (Cancelled)

19. (Currently Amended) An ~~image sensor~~ imager device, comprising:

a clear package, ~~having a rectangular~~ said clear package comprising an outer perimeter ~~with image acquiring surfaces and an internal cavity~~ defined within said ~~rectangular~~ outer perimeter, said outer perimeter comprising a plurality of first electrical connections; and

an imager die within said internal cavity, said imager die comprising an image sensor, obtaining image information that is incident from both a first image acquiring

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~~surface and from a second opposite image acquiring surface~~ and a plurality of second electrical connections coupled to said plurality of first electrical connections,

wherein said clear package completely surrounds said imager die and is transparent in all directions.

20. (Currently Amended) An ~~image sensor~~ imager device as in claim 19, wherein said ~~image sensor includes first and second image sensors facing in opposite directions~~ clear package is a quad flat package.

21. (Currently Added) An imager device as in claim 19, wherein said clear package comprises acrylic.

22. (Currently Added) An imager device as in claim 19, wherein said image sensor is a CMOS imager array.

23. (Currently Added) An imager device as in claim 19, wherein said plurality of first electrical connections extends around said perimeter.

24. (Currently Added) An imager device as in claim 19, further comprising a window configured to block photons from said image sensor.
